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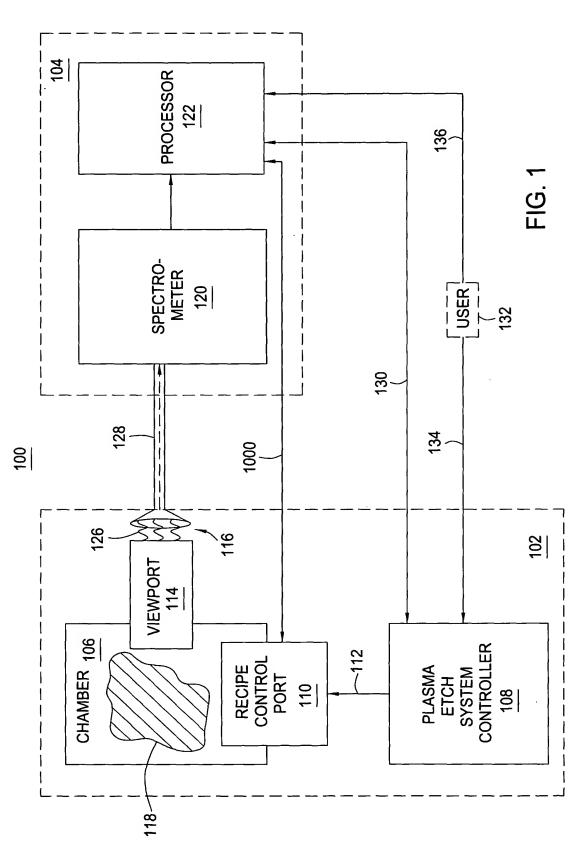
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Applicant: Davis et al.
Title: METHOD FOR AUTOMATIC DETERMINATION OF SEMICONDUCTOR PLASMA CHAMBER MATCHING AND SOURCE OF FAULT BY COMPREHENSIVE PLASMA MONITORING

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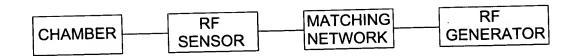


FIG. 2

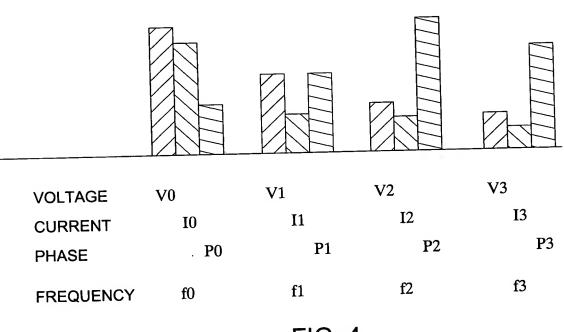
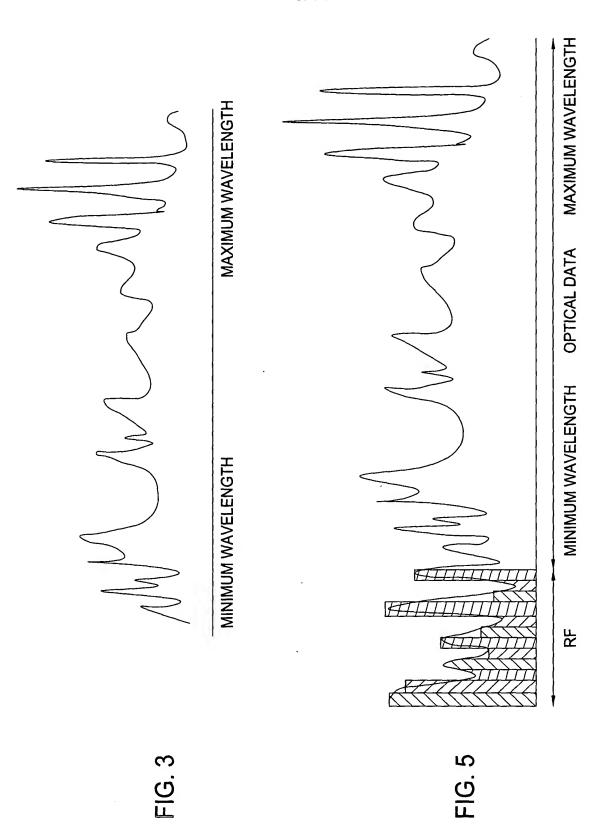


FIG. 4

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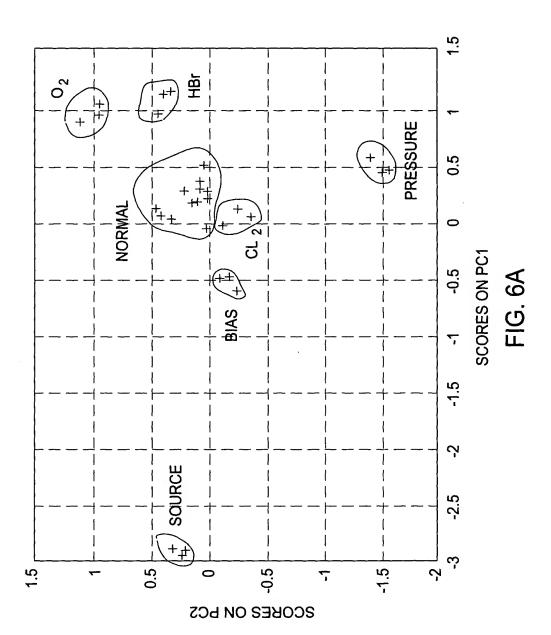
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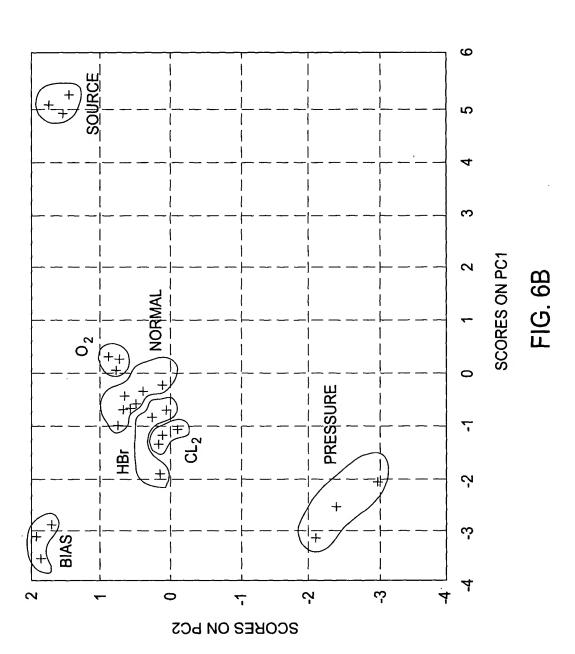
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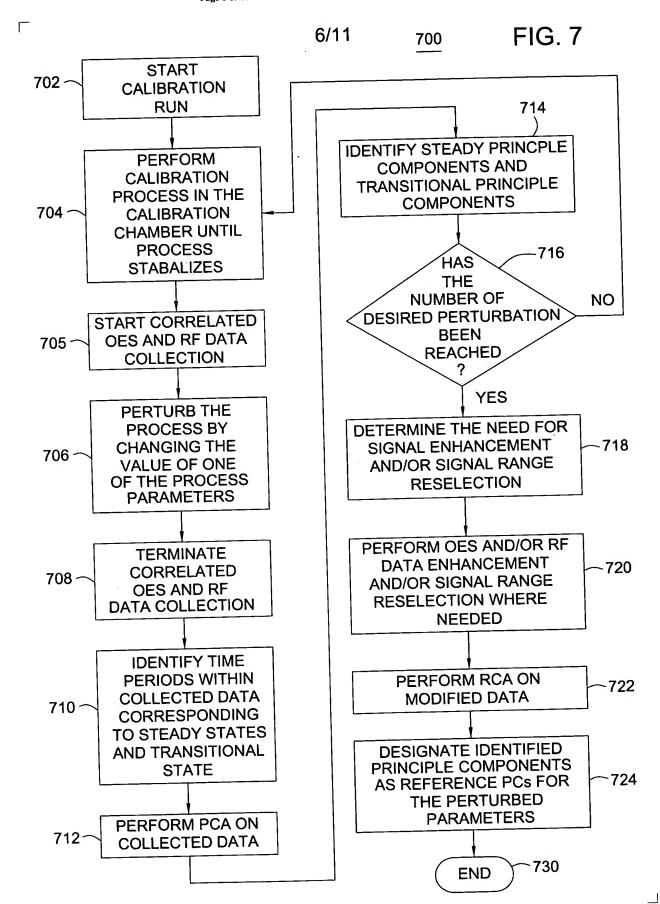
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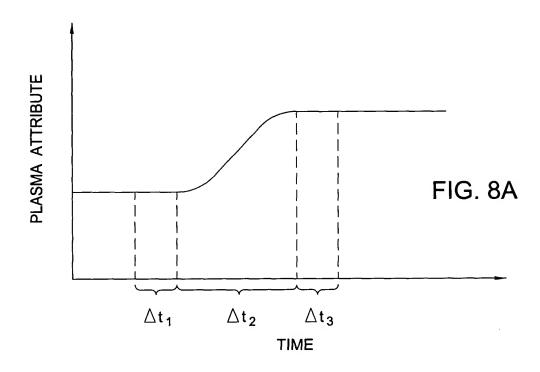
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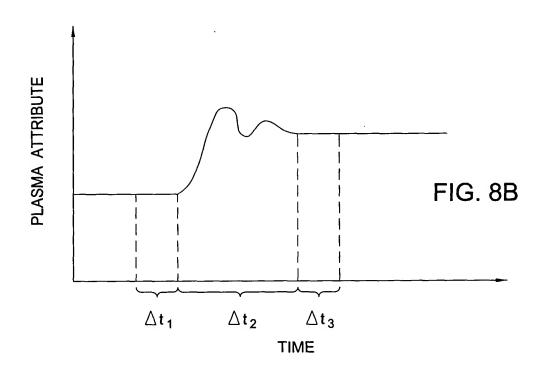


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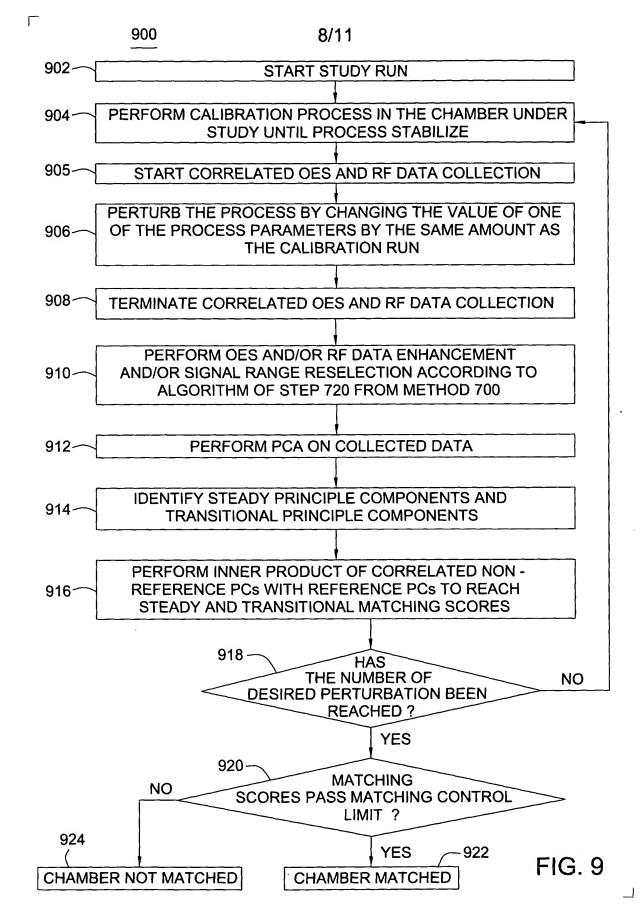
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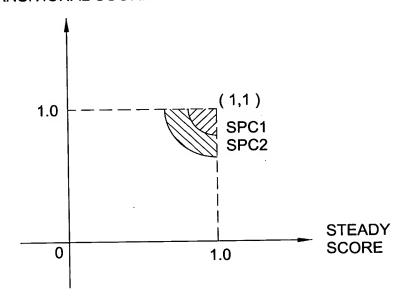


FIG. 10

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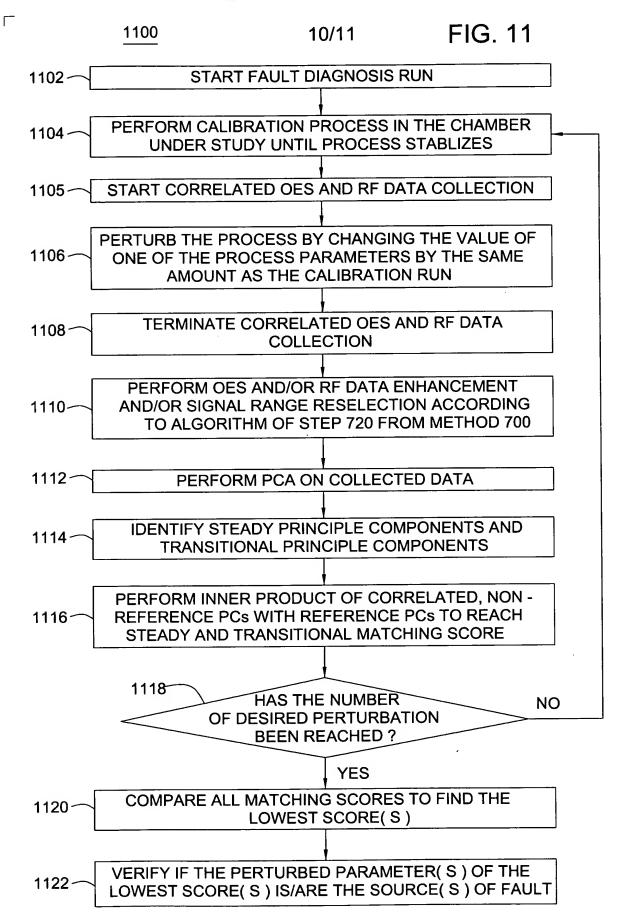
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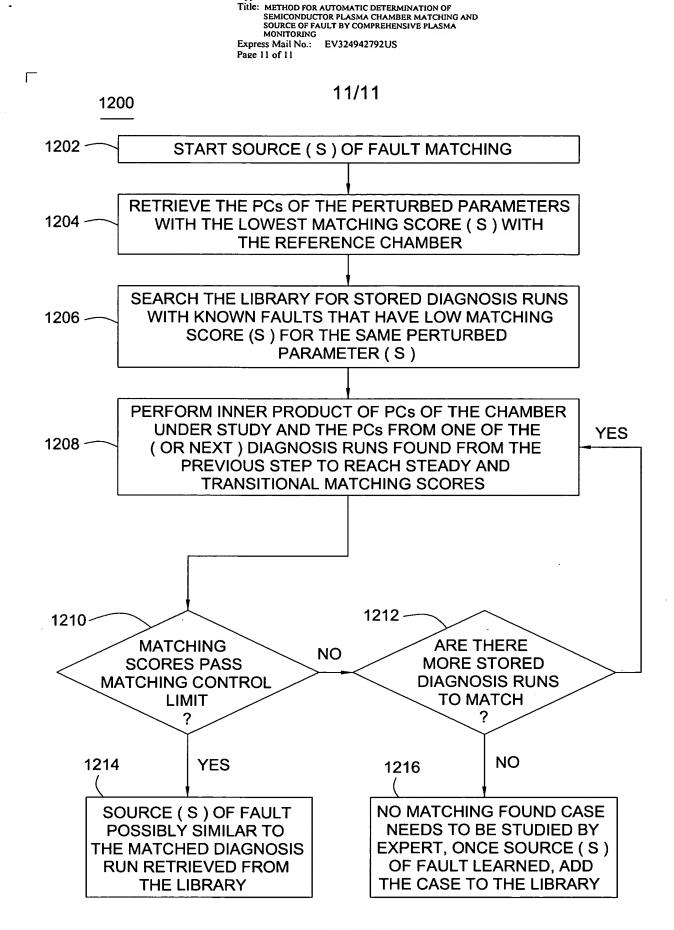
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FIG. 12

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